

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-7. (Canceled)

8. (Previously Presented) A ceramic electronic component comprising:  
a ceramic substrate;  
a conductive layer which is formed in at least one of the inside and outside of the ceramic substrate and comprises a metal particle and a metal oxide particle,

wherein said metal oxide particle which has an average particle size of 5 to 60 nm and a melting point of 1500°C or higher, and

wherein a content of the metal oxide particle is 0.1 to 10.0 wt% based on the amount of the metal particle; and

a capacitor formed by including the ceramic substrate and the conductive layer, wherein, in the conductive layer, the metal particle is at least one kind selected from nickel and nickel alloys, and the metal oxide particle is an oxide compound comprising at least one kind of metals selected from magnesium, aluminum, titanium and zirconium.

9. (Previously Presented) A ceramic electronic component comprising:

a ceramic substrate;  
a conductive layer which is formed in at least one of the inside and outside of the ceramic substrate and comprises a metal particle and a metal oxide particle,

wherein said metal oxide particle which has an average particle size of 5 to 60 nm and a melting point of 1500°C or higher, and

wherein a content of the metal oxide particle is 0.1 to 10.0 wt% based on the amount of the metal particle; and

an insulator formed by including the ceramic substrate and the conductive layer, wherein, in the conductive layer, the metal particle is at least one kind selected from silver and silver alloys, and the metal oxide particle is an oxide compound comprising at least one kind of metals selected from magnesium, aluminum, titanium and zirconium.

10-11. (Canceled)